

Rogers, Daniel

From: J. Jiao <j_jiao@hotmail.com>
Sent: Friday, November 18, 2016 11:39 AM
To: Rogers, Daniel; 'Jantz-Sell, Taylor'
Subject: Re: Updated ENERGY STAR Requirements for the Use of LM-80 Data document for stakeholder review

Dear Taylor and Dan,

I had some discussions with Dan during the ASSIST meeting, and would like to provide you the comments as following.

1. In regards to **Successor d “The same type(s) of deposition processes employed”**:

It is unclear the mentioned deposition processes are for wafer deposition or for phosphor deposition. To avoid confusion, it is suggested to change to “The same type(s) of **overall** processes”.

2. In regards to **Successor i “Equal or lower average current density per LED die (i.e., mA/mm²)”**:

When using multi-junction technology (MJT), an LED die can be sub-divided into sub-cells. With different electrical configurations, the same LED die of the size may be configured such that each sub-cell has lower current density but higher voltage, or higher current density but lower voltage, with the total power of the LED die remain unchanged. Thus, but requiring the “average current density per LED die” is no longer sufficient to cover this case. Therefore, it is recommended to change to “Average current density **or power density** per LED die (i.e., mA/mm²)”.

3. AC LED packages, modules and arrays.

Because ANSI RP-16 does not define AC LEDs, modules and arrays, the Section 2 Definition as it is written now does not give the explanation how these products are included. These products are now can be tested per ANSI/IES LM-80-15. Therefore, please **provide additional statements in Section 2 to including AC LEDs**.

Let me know if you have any questions. Thank you.

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